Adv Motion Detector Using PIR Sensors

Project Title: PIR Motion Detector 2.0

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Contact: http://www.ti.com/support

Public Release

Assembly Variant: 001

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Version control disabled

SVN Rev: TIDA-01069

Number: Rev: E1

TID #: 01069

Orderable: ChangeMe!

Revision History

<table>
<thead>
<tr>
<th>Rev</th>
<th>ECN #</th>
<th>Approved Date</th>
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<tbody>
<tr>
<td>N/A</td>
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</tbody>
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Component List:

- PIR Sensor 1: Middle Beam
- PIR Sensor 2: Lower Beam
- OP AMP
- Comparator
- TLV3691
- Comparator
- ESD Protection
- Booster Pack Pinout
- 3.3V
- Digital Comparator Output/Data Ready
- 16 bit ADC +PGA +Reference +Comparator
- ADS 1114
- TPS 610981
- Alkaline Battery
- OP AMP
- Vref = 3.3V/2
- TLV369
- OPT 3002
- Light Sensor
- HDC 1010
- Humidity Temperature Sensor
- I2C
- I2C

Note: Vref is 3.3V/2.
Fresnel Lenses

Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
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<td>002</td>
<td>ChangeMe!</td>
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Assembly Note

ZZ1
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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